Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1067	374/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/09 20:28
<b>S2</b>	368	374/137.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/09 19:42
S3	296	374/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 13:33
S4	1128	374/141.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 14:14
S5	15	"4892707"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/17 14:35
S6	145	"374"/\$.ccls. and photon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/09 19:43
S7	204	"374"/\$.ccls. and photon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:43
58	96	"374"/\$.ccls. and photon and flow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:46
S9	1515	"374"/\$.ccls. and radiation and flow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:47

S10	792	"374"/\$.ccls. and radiation and flow\$4 and (semiconductor or electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:48
S11	503	"374"/\$.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:52
S12	203	"374"/\$.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:04
S13	106	"374"/\$.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:04
S14	25	"374"/\$.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution) and (heat adj sink)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:07
S15	0	374/147.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:08
S16	0	374/152.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:08
S17	9	374/141.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:09
S18	19	374/121.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:09
S19	. 14	374/137.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:09

S20	17	374/124.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:09
S21	6	374/45.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:09
S22	5	374/5.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	∕ON	2004/11/09 20:09
S23	2	374/57.ccls. and radiation and flow\$4 and (semiconductor or electronic) and cool\$3 and ((thermal or temperature) NEAR distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:20
S24	0	(radiation NEAR deterct\$3) and (semiconductor or electronic) and cool\$3 and (heat adj (sink or exchang\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:21
S25	489	(radiation NEAR detect\$3) and (semiconductor or electronic) and cool\$3 and (heat adj (sink or exchang\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:21
S26	370	(radiation NEAR detect\$3) and (semiconductor or electronic) and cool\$3 and (heat adj (sink or exchang\$4)) and flow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:24
S27	6	"6251706"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:26
S28	27	"5844208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:26
S29	7	"6349032"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 20:27

S38	331	374/124.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 13:36
S39	129	374/124.ccls. and cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 13:37
S40	129	374/124.ccls. and cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ÓR <sub>,</sub>	ON	2004/11/10 13:37
S41	129	374/124.ccls. and cool\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 13:37

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	372	374/137.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:05
L2	331	374/124.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:05
L3 -	1073	374/121.ccls.	US-PGPUB;	OR	OFF	2004/11/10 16:06
			USPAT; EPO; JPO;			
	* ·		DERWENT; IBM_TDB			
L4	1136	374/141.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L5	183	374/147.ccls.	US-PGPUB;	OR	OFF	2004/11/10 16:06
			USPAT; EPO; JPO;			
			DERWENT; IBM_TDB			
L6	188	374/152.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L7	79	374/125.ccls.	US-PGPUB;	OR	OFF	2004/11/10 16:06
			USPAT; EPO; JPO;			
			DERWENT; IBM_TDB			7
L8	245	374/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
Ĺ9	406	374/57.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:07

L10	59	374/47.ccls.	US-PGPUB; USPAT; EPO; JPO;	OR	OFF	2004/11/10 16:07
			DERWENT;			
			IBM_TDB			

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	372	374/137.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:05
L2	331	374/124.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:05
L3	1073	374/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L4	1136	374/141.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L5	183	374/147.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L6	188	374/152.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L7	79	374/125.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L8	245	374/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:06
L9	406	374/57.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:07

L10	59	374/47.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:08
L11	59733	(semiconductor or (integrated adj circuit) or electronic) and (heatsink or (heat adj sink) or (heat adj exchang\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 16:08
L12	68342	(semiconductor or (integrated adj circuit) or electronic) and (heatsink or (heat adj sink) or (heat adj exchang\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:09
L13	.4704	(semiconductor or (integrated adj circuit) or electronic) NEAR (heatsink or (heat adj sink) or (heat adj exchang\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:09
L14	2163	(semiconductor or (integrated adj circuit) or electronic) NEAR (heatsink or (heat adj sink) or (heat adj exchang\$3)) and (cool\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:09
L15	1191	(semiconductor or (integrated adj circuit) or electronic) NEAR (heatsink or (heat adj sink) or (heat adj exchang\$3)) and (cool\$6) and flow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:09
L16	989	(semiconductor or (integrated adj circuit) or electronic) NEAR (heatsink or (heat adj sink) or (heat adj exchang\$3)) and (cool\$6) and flow\$4 and (air or fluid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:18
L17	1678	"361"/\$.ccls. and (coolant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:18
L18	1432	"361"/\$.ccls. and (coolant) and flow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:19
L19	590	"361"/\$.ccls. and (coolant) and flow\$4 and (semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 16:23

L20	59	"361"/\$.ccls. and (coolant) and flow\$4 and (semiconductor) and duct	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/11/10 16:23
			IBM_TDB			